

# SMD1210P Series

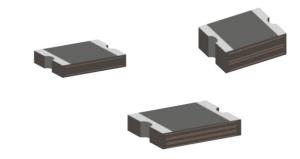
# **POSITIVE THERMAL COEFFICIENT(PTC)**

#### Description

The 1210 series provides miniature surface mount over-current protection with holding current from 0.05A to 2.60A. This series is suitable for wide range of applications in modern electronics where space is limited

#### Features

- I I(hold): 0.05~2.60A
- I Very high voltage surge capabilities
- I Available in lead-free version
- I Fast response to fault current
- I RoHS compliant, Lead- Free and Halogen-Free
- I Low resistance
- I Compact design saves board space
- I Compatible with high temperature solders

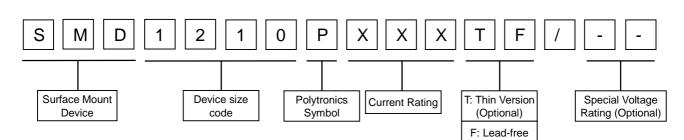


#### Applications

- I USB peripherals
- I Disk drives
- I CD-ROMs
- I General electronics
- I Disk drives
- I Set-top-box and HDMI
- I Mobile Internet Device (MID)

- I PDAs / digital cameras
- I Game console port protection
- Plug and play protection for motherboards and peripherals
- I Mobile phones battery and port protection

#### Part Number Code



#### **Environmental Specifications**

Test	Test Conditions	Accept/Reject Criteria
Resistance	In still air @ 25°C	$R_{min} \leq R \leq R_{max}$
Time to Trip	Specified current, $V_{max}$ , 25°C	T≤maximum Time to Trip
Hold Current	30min, at I <sub>H</sub>	No trip
Trip Cycle Life	Vmax, Imax, 100cycles	No arcing or burning
Trip Endurance	Vmax, 1 hours	No arcing or burning



### Physical Characteristics and Environmental Specifications

Terminal materials :	Tin-Plated Nickle-copper				
Soldering zone	Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.				
Environmental Specification	S				
Test	Conditions	Resistance Change			
Passive aging	85°C,1000hours	±10%			
Humidity aging	85°C/85%RH.1000 hours	±5%			
Thermal shock	MIL-STD-202,Method 107G	-30% typical resistance change			
	+85°C/-40°C,20times				
Solvent Resistance	MIL-STD-202,Method 215 no change				
Vibration	ML-STD-883C, Test Condition A	No change			

# Electrical Characteristic

	$V_{Max}$	I <sub>Max</sub>	I <sub>Hold</sub>	I <sub>Trip</sub>	P <sub>D</sub>	Maximum Ti	me-to-trip	Resis	tance
Part Number		(4)	( )	( • )	Max.	Current	Time	R <sub>Min</sub>	R1 <sub>Max</sub>
	(Vdc)	(A)	(A)	(A)	(W)	(A)	(Sec)	(Ω)	(Ω)
SMD1210P005TF	60	100	0.05	0.15	0.6	0.25	1.50	2.8	50
SMD1210P010TF	30	100	0.10	0.30	0.6	0.50	0.60	0.8	15
SMD1210P020TF	30	100	0.20	0.40	0.6	8.0	0.02	0.40	5
SMD1210P035TF/30	30	100	0.35	0.75	0.6	8.0	0.20	0.20	1.3
SMD1210P035TF	16	100	0.35	0.75	0.6	8.0	0.20	0.20	1.3
SMD1210P050TF	16	100	0.50	1.00	0.6	8.0	0.10	0.18	0.9
SMD1210P075TF	6	100	0.75	1.50	0.6	8.0	0.10	0.07	0.4
SMD1210P075TF/24	24	100	0.75	1.50	0.6	8.0	0.10	0.07	0.45
SMD1210P110TF	6	100	1.10	2.20	0.6	8.0	0.30	0.05	0.21
SMD1210P110TF/12	12	100	1.10	2.20	0.8	8.0	0.30	0.05	0.25
SMD1210P110TF/16	16	100	1.10	2.20	0.8	8.0	0.30	0.05	0.25
SMD1210P150TF	6	100	1.50	3.00	0.8	8.0	0.50	0.03	0.11
SMD1210P175TF	6	100	1.75	3.50	0.8	8.0	0.60	0.02	0.08
SMD1210P200TF	6	100	2.00	4.00	0.8	8.0	1.00	0.015	0.07

 $V_{max}$  = Maximum operating voltage vice can withstand without damage at rated current (Imax).

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V max).

I hold = Hold Current. Maximum current device will not trip in 25°C still air.

I trip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

 $P_d$  = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Ri min/max = Minimum/Maximum device resistance prior to tripping at 25°C.

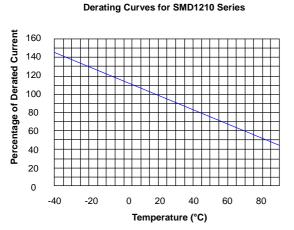
R1<sub>max</sub> = Maximum device resistance is measured one hour post reflow.



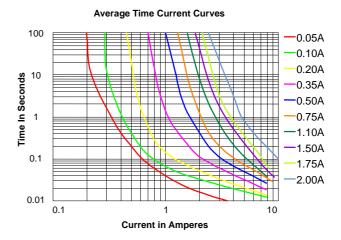
### Thermal Derating Chart-I<sub>H</sub> (A)

Dout Number			Maximu	m ambient	operating	temperatu	ires ( °C )		
Part Number	-40	-20	0	25	40	50	60	70	85
SMD1210P005TF	0.08	0.07	0.06	0.05	0.04	0.04	0.03	0.03	0.02
SMD1210P010TF	0.16	0.14	0.12	0.10	0.08	0.07	0.06	0.05	0.05
SMD1210P020TF	0.29	0.26	0.22	0.20	0.16	0.14	0.13	0.11	0.08
SMD1210P035TF	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
SMD1210P035TF/30	0.47	0.45	0.40	0.35	0.33	0.28	0.24	0.21	0.18
SMD1210P050TF	0.76	0.67	0.58	0.50	0.43	0.40	0.36	0.32	0.28
SMD1210P075TF	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
SMD1210P075TF/24	1.00	0.97	0.86	0.75	0.64	0.59	0.54	0.48	0.40
SMD1210P110TF	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210P110TF/12	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210P110TF/16	1.60	1.42	1.26	1.10	0.94	0.86	0.80	0.70	0.58
SMD1210P150TF	2.30	2.02	1.76	1.50	1.24	1.11	1.00	0.85	0.65
SMD1210P175TF	2.45	2.22	2.01	1.75	1.45	1.26	1.10	0.98	0.80
SMD1210P200TF	2.60	2.44	2.35	2.00	1.78	1.67	1.50	1.45	1.10

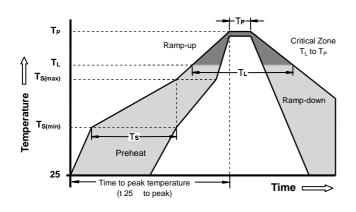
## **Thermal Derating Curve**



# Average Time-Current Curve

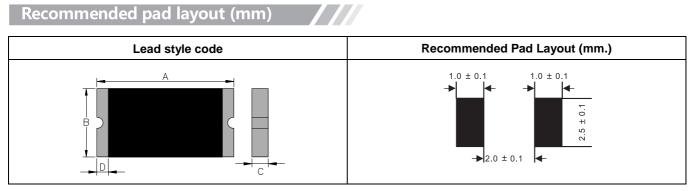






Reflow Condition		Pb - Free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	- Time (min to max) (t <sub>s</sub> )	60 -180 Seconds	
•	e ramp up rate ( Liquids <sub>L</sub> ) to peak	3°C/second max	
T <sub>S(max)</sub> to	o TL - Ramp-up Rate	3°C/second max	
Reflo	<ul> <li>Temperature (T<sub>L</sub>)</li> <li>(Liquids)</li> </ul>	217°C	
w	- Time (min to max) (t <sub>s</sub> )	60 -150 Seconds	
Peak Te	emperature (T <sub>P</sub> )	260 +0/-5°C	
	thin 5°C of actual peak ature (t <sub>P</sub> )	20 - 40 Seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max	
Do not exceed		260°C	

### Recommended pad layout (mm)



## Product Dimensions

# Unit : mm

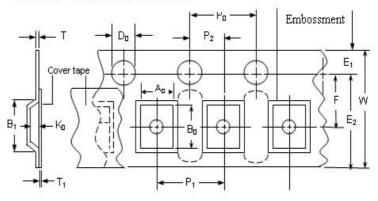
Part Number	Marking	A	۱	I	В	(	2	D	E
Part Number	Marking	Max	Min	Max	Min	Max	Min	Min	Min
SMD1210P005TF	JN	3.00	3.43	2.35	2.80	0.60	1.25	0.15	0.10
SMD1210P010TF	JN	3.00	3.43	2.35	2.80	0.60	1.25	0.15	0.10
SMD1210P020TF	JF	3.00	3.43	2.35	2.80	0.50	1.00	0.15	0.10
SMD1210P035TF	JB	3.00	3.43	2.35	2.80	0.35	0.90	0.15	0.10
SMD1210P035TF/30	JB	3.00	3.43	2.35	2.80	0.35	1.00	0.15	0.10
SMD1210P050TF	JG	3.00	3.43	2.35	2.80	0.35	0.90	0.15	0.10
SMD1210P075TF	JA	3.00	3.43	2.35	2.80	0.35	0.85	0.15	0.10
SMD1210P075TF/24	JA	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210P110TF	JK	3.00	3.43	2.35	2.80	0.40	1.00	0.15	0.10
SMD1210P110TF/12	JK	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210P110TF/16	JK	3.00	3.43	2.35	2.80	0.50	1.10	0.15	0.10
SMD1210P150TF	JK	3.00	3.43	2.35	2.80	0.60	1.40	0.15	0.10
SMD1210P175TF	JK	3.00	3.43	2.35	2.80	0.60	1.40	0.15	0.10
SMD1210P200TF	JK	3.00	3.43	2.35	2.80	0.60	1.50	0.15	0.10



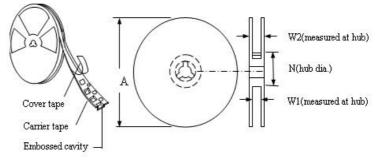
## Taping and Reel Specifications

Covering Specifications					
EIA 481-1(Unit:mm)					
W	8.0± 0.3				
P0	4.0 ± 0.10				
P <sub>1</sub>	4.0 ± 0.10				
P <sub>2</sub>	2.0 ± 0.05				
A <sub>0</sub>	2.87± 0.10				
B <sub>0</sub>	3.56± 0.10				
D <sub>0</sub>	1.55 ± 0.05				
F	3.5 0± 0.05				
E1	1.75 ± 0.10				
Т	0.25 ± 0.10				
Leader min.	390				
Trailer min.	160				
Reel I	Dimensions				
A	178±1.0				
N	59±1				
W <sub>1</sub>	8.5+1.0/-0.2				
W <sub>2</sub>	12.0±1				

#### ELA Tape Component Dimentions



#### **EIA Reel Dimentions**



## Packaging Quantity

Quantity	3000			4000
	SMD1210P175TF	SMD1210P200TF	SMD1210P005TF	SMD1210P010TF
			SMD1210P020TF	SMD1210P035TF/30
			SMD1210P035TF	SMD1210P050TF
Part Number			SMD1210P075TF	SMD1210P075TF/24
			SMD1210P110TF	SMD1210P110TF/12
			SMD1210P110TF/16	SMD1210P150TF

单击下面可查看定价,库存,交付和生命周期等信息

>>SUNMATE(森美特)